



Material Content Data Sheet



Sales Product Name		TLE8080EM		Issued		20. July 2018		
MA#		MA001661894						
Package		PG-SSOP-24-9		Weight*		150.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.456	2.29	2.29	22902	22902
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8914	
wire	non noble metal	copper	7440-50-8	54.617	36.20	37.14	361964	371435
	non noble metal	copper	7440-50-8	0.866	0.57	0.57	5740	5740
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1145
encapsulation	plastics	epoxy resin	-	7.946	5.27		52659	
	inorganic material	silicondioxide	60676-86-0	78.249	51.86	57.24	518582	572386
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19292	19292
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.252	0.17		1673	
	noble metal	silver	7440-22-4	0.757	0.50	0.67	5019	6692
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com